Small Outline Package

Applications:

- Power Management (DC-DC, AC-DC)
- LED Driver
- Flash Memory (Nor Flash, EEPROM)
- Industry Controller

Features:

- JEDEC Standard package outlines
- Au, Cu, Ag-alloy, Al bonding process capabilities
- Multi-chip capability for stack or flat lie
- Exposed die pad packaging (eSOP)
- Lack Pin6 or Pin7 is optional for SOP 7L
- Component surface mount capability

Reliability Condition:

- Moisture Sensitivity Pre-condition :
  -MSL3: 192hrs@30°C/60% RH
  -MSL1: 168hrs@85°C/85% RH
- Temperature Cycle: 500 cycles @ -65°C /+150°C
- uHAST: 96hrs @130°C/85% RH
- High Temperature Storage: 1000hrs@150°C

Package Outlines Dimensions:

Package	Body Size (mm)	Footprint (mm)	Stand Off (mm)	Lead Pitch (mm)	Total Height (mm)
SOP 8L	3.9*4.9*1.4	6.0	0.15	1.27	1.55
SOP 7L	3.9*4.9*1.4	6.0	0.15	1.27	1.55

Copyright @ Microbonding.cn 2016 Rev 1